

**What is claimed is:**

1       1. A heat dissipating apparatus for an electronic  
2 device having an integrated heat spreader, comprising:

3            a base having a lower surface and an upper surface,  
4            the lower surface having a contact area to  
5            contact the integrated heat spreader when the  
6            base is disposed on the electronic device, and  
7            the lower surface having a concave area  
8            extended to the contact area from an edge of  
9            the lower surface of the base.

1       2. The heat dissipating apparatus as claimed in  
2 claim 1, wherein the contact area of the base is  
3 connected to the integrated heat spreader by means of  
4 thermal paste.

1       3. The heat dissipating apparatus as claimed in  
2 claim 2, wherein the thermal paste is composed of a phase  
3 change material.

1       4. The heat dissipating apparatus as claimed in  
2 claim 1, wherein the base further comprises a plurality  
3 of fins formed on the upper surface thereof.

1       5. The heat dissipating apparatus as claimed in  
2 claim 1, wherein the cross section of the concave area is  
3 rectangular.

1       6. The heat dissipating apparatus as claimed in  
2 claim 1, wherein the cross section of the concave area is  
3 semicircular.

. 1        7. The heat dissipating apparatus as claimed in  
2        claim 1, wherein the cross section of the concave area is  
3        triangular.

. 1        8. The heat dissipating apparatus as claimed in  
2        claim 1, wherein the integrated heat spreader and contact  
3        area are substantially rectangular.

. 1        9. The heat dissipating apparatus as claimed in  
2        claim 1, wherein the electronic device is a central  
3        processing unit (CPU).

. 1        10. A heat dissipating apparatus, disposed on an  
2        electronic device having an integrated heat spreader,  
3        comprising:

. 4              a base having a concave area and a contact area,  
5              wherein the contact area is connected to the  
6              integrated heat spreader, the shape and  
7              position of the contact area correspond to the  
8              shape and position of the integrated heat  
9              spreader, and the concave area is extended to  
10             the contact area from an edge of the base; and  
11             a thermal paste disposed between the contact area  
12             and integrated heat spreader.

. 1        11. The heat dissipating apparatus as claimed in  
2        claim 10, wherein the thermal paste is composed of a  
3        phase change material.

. 1        12. The heat dissipating apparatus as claimed in  
2        claim 10, wherein the base further comprises a plurality  
3        of fins formed thereon.

1           13. The heat dissipating apparatus as claimed in  
2        claim 10, wherein the cross section of the concave area  
3        is rectangular.

1           14. The heat dissipating apparatus as claimed in  
2        claim 10, wherein the cross section of the concave area  
3        is semicircular.

1           15. The heat dissipating apparatus as claimed in  
2        claim 10, wherein the cross section of the concave area  
3        is triangular.